



Material Content Data Sheet



Sales Product Name		BSP372N H6327		Issued		25. September 2017		
MA#		MA001100396						
Package		PG-SOT223-4-21		Weight*		113.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.011	0.01		94	
	noble metal	gold	7440-57-5	0.041	0.04		363	
	inorganic material	silicon	7440-21-3	0.630	0.55	0.60	5542	5999
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1339	
	non noble metal	copper	7440-50-8	50.489	44.44	44.62	444369	446243
wire	non noble metal	copper	7440-50-8	0.103	0.09	0.09	910	910
encapsulation	organic material	carbon black	1333-86-4	0.602	0.53		5294	
	plastics	epoxy resin	-	9.023	7.94		79417	
	inorganic material	silicondioxide	60676-86-0	50.531	44.48	52.95	444737	529448
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12885	12885
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4515	4515
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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